

High speed 1200 V TRENCHSTOP™ IGBT 7 Technology co-packed with full rated current, soft-commutating, ultra-fast recovery and low Q_{rr} emitter controlled 7 Rapid diode

Features

- $V_{CE} = 1200\text{ V}$
- $I_C = 50\text{ A}$
- Maximum junction temperature $T_{vjmax} = 175^\circ\text{C}$
- Best-in-class high speed IGBT co-packed with full rated current, low Q_{rr} and soft-commutating high speed diode
- Low saturation voltage $V_{CEsat} = 1.7\text{ V}$ at $T_{vj} = 25^\circ\text{C}$
- Optimized for high efficiency in high speed hard switching topologies (2-L inverter, 3-L NPC T-type, ...)
- Easy paralleling capability due to positive temperature coefficient in V_{CEsat}
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: <http://www.infineon.com/igbt/>

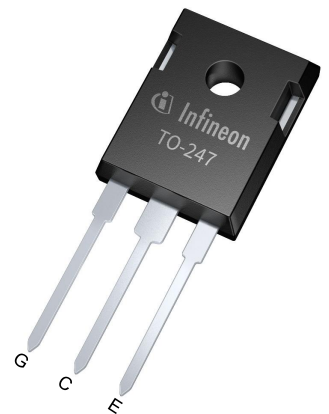
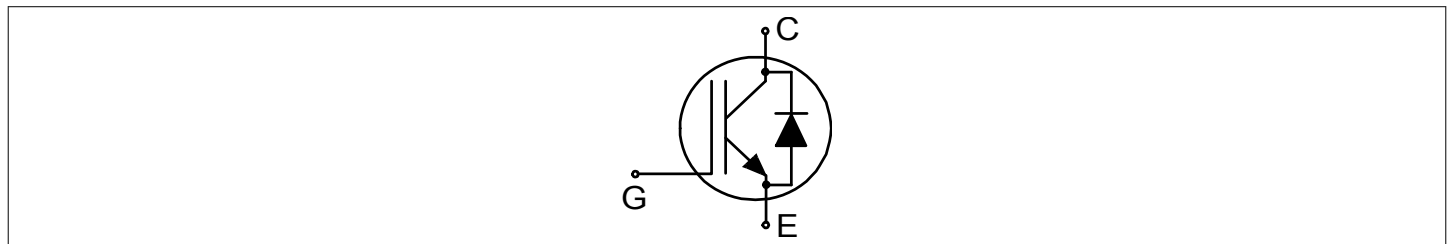
Potential applications

- Industrial UPS
- EV-Charging
- String inverter
- Welding

Product validation

- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22

Description



Type	Package	Marking
IKW50N120CH7	PG-TO247-3-STD-NN2.5	K50MCH7

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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in.) from case	L_E			13		nH
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	M	M3 screw, Maximum of mounting process: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W
IGBT thermal resistance, junction-case	$R_{th(j-c)}$			0.29	0.38	K/W
Diode thermal resistance, junction-case	$R_{th(j-c)}$			0.5	0.65	K/W

2 IGBT

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Collector-emitter voltage	V_{CE}	$T_{vj} \geq 25\text{ °C}$	1200	V	
DC collector current, limited by T_{vjmax}	I_C	limited by bondwire	$T_c = 25\text{ °C}$	86	A
			$T_c = 100\text{ °C}$	73	
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpulse}		200	A	
Turn-off safe operating area		$V_{CC} \leq 800\text{ V}$, $V_{CE,peak} < 1200\text{ V}$, $V_{GE} = 0/15\text{ V}$, $R_{Goff} \geq 8\ \Omega$, $T_{vj} \leq 175\text{ °C}$	200	A	
Gate-emitter voltage	V_{GE}		± 20	V	
Transient gate-emitter voltage	V_{GE}	$t_p \leq 0.5\ \mu\text{s}$, $D < 0.001$	± 25	V	
Power dissipation	P_{tot}		$T_c = 25\text{ °C}$	398	W
			$T_c = 100\text{ °C}$	199	

Table 3 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	V_{CEsat}	$I_C = 50\text{ A}$, $V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$	1.7	2.15	V
			$T_{vj} = 175\text{ °C}$	2		

(table continues...)
 Datasheet

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Gate-emitter threshold voltage	V_{GEth}	$I_C = 0.8 \text{ mA}, V_{CE} = V_{GE}$	4.7	5.5	6.2	V
Zero gate-voltage collector current	I_{CES}	$V_{CE} = 1200 \text{ V}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$		40	μA
			$T_{vj} = 175 \text{ °C}$		3500	
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}$			100	nA
Transconductance	g_{fs}	$I_C = 50 \text{ A}, V_{CE} = 20 \text{ V}$		91		S
Input capacitance	C_{ies}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$		6.6		nF
Output capacitance	C_{oes}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$		133		pF
Reverse transfer capacitance	C_{res}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$		37		pF
Gate charge	Q_G	$I_C = 50 \text{ A}, V_{GE} = 15 \text{ V}, V_{CC} = 960 \text{ V}$		375		nC
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		39	ns
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		37	
Rise time (inductive load)	t_r	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		27	ns
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		30	
Turn-off delay time	$t_{d(off)}$	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		319	ns
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		387	
Fall time (inductive load)	t_f	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		41	ns
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		127	
Turn-on energy	E_{on}	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		2.33	mJ
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		3.49	
Turn-off energy	E_{off}	$V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{G(on)} = 8 \text{ }\Omega, R_{G(off)} = 8 \text{ }\Omega$	$T_{vj} = 25 \text{ °C}, I_C = 50 \text{ A}$		1.12	mJ
			$T_{vj} = 175 \text{ °C}, I_C = 50 \text{ A}$		2.74	

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Total switching energy	E_{ts}	$V_{CC} = 600\text{ V}, V_{GE} = 0/15\text{ V}, R_{G(on)} = 8\ \Omega, R_{G(off)} = 8\ \Omega$	$T_{vj} = 25\text{ }^\circ\text{C}, I_C = 50\text{ A}$		3.45		mJ
			$T_{vj} = 175\text{ }^\circ\text{C}, I_C = 50\text{ A}$		6.23		
Operating junction temperature	T_{vj}		-40		175	$^\circ\text{C}$	

Note: Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified.

3 Diode

Table 4 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Diode forward current, limited by T_{vjmax}	I_F	limited by bondwire	$T_c = 25\text{ }^\circ\text{C}$	77	A
			$T_c = 100\text{ }^\circ\text{C}$	51	
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpulse}		200	A	
Power dissipation	P_{tot}		$T_c = 25\text{ }^\circ\text{C}$	231	W
			$T_c = 100\text{ }^\circ\text{C}$	115	

Table 5 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Diode forward voltage	V_F	$I_F = 50\text{ A}$	$T_{vj} = 25\text{ }^\circ\text{C}$		2.5	3	V
			$T_{vj} = 175\text{ }^\circ\text{C}$		2.3		
Diode reverse recovery time	t_{rr}	$V_R = 600\text{ V}, R_{G(on)} = 8\ \Omega$	$T_{vj} = 25\text{ }^\circ\text{C}, I_F = 50\text{ A}$		116		ns
			$T_{vj} = 175\text{ }^\circ\text{C}, I_F = 50\text{ A}$		194		
Diode reverse recovery charge	Q_{rr}	$V_R = 600\text{ V}, R_{G(on)} = 8\ \Omega$	$T_{vj} = 25\text{ }^\circ\text{C}, I_F = 50\text{ A}$		1.48		μC
			$T_{vj} = 175\text{ }^\circ\text{C}, I_F = 50\text{ A}$		3.71		
Diode peak reverse recovery current	I_{rrm}	$V_R = 600\text{ V}, R_{G(on)} = 8\ \Omega$	$T_{vj} = 25\text{ }^\circ\text{C}, I_F = 50\text{ A}$		28		A
			$T_{vj} = 175\text{ }^\circ\text{C}, I_F = 50\text{ A}$		41		

(table continues...)

Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Diode peak rate of fall of reverse recovery current	di_{rr}/dt	$V_R = 600 \text{ V}, R_{G(on)} = 8 \Omega$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_F = 50 \text{ A}$		-383		A/ μs
			$T_{vj} = 150 \text{ }^\circ\text{C},$ $I_F = 50 \text{ A}$		-323		
Reverse recovery energy	E_{rec}	$V_R = 600 \text{ V}, R_{G(on)} = 8 \Omega$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_F = 50 \text{ A}$		0.43		mJ
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_F = 50 \text{ A}$		1.22		
Operating junction temperature	T_{vj}		-40		175	$^\circ\text{C}$	

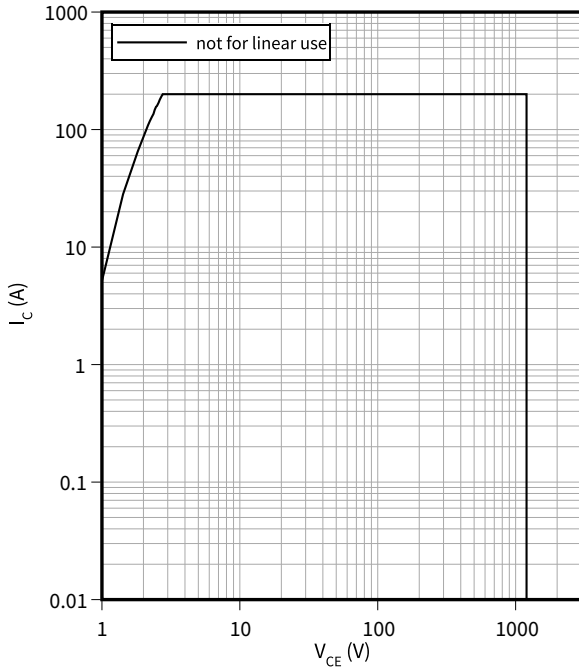
Note: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Dynamic test circuit, parasitic inductance $L_\sigma = 30 \text{ nH}$, $C_\sigma = 18 \text{ pF}$

4 Characteristics diagrams

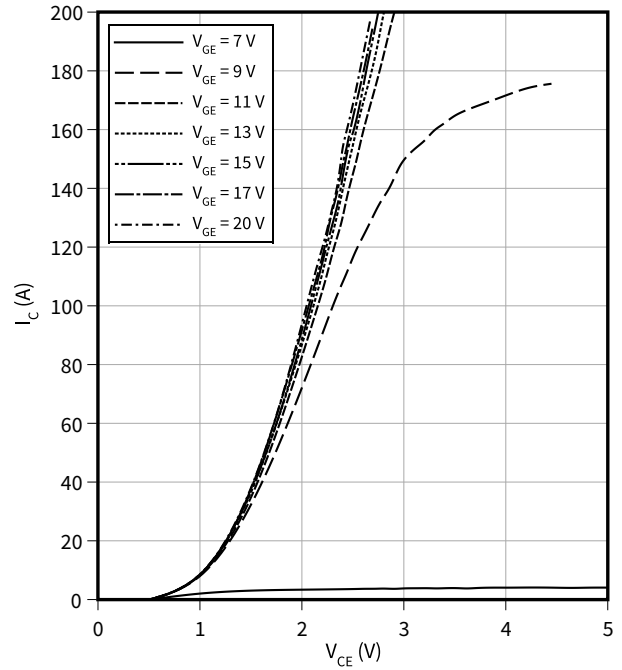
Reverse bias safe operating area

$I_C = f(V_{CE})$
 $T_{vj} \leq 175\text{ °C}, V_{GE} = 0/15\text{ V}$



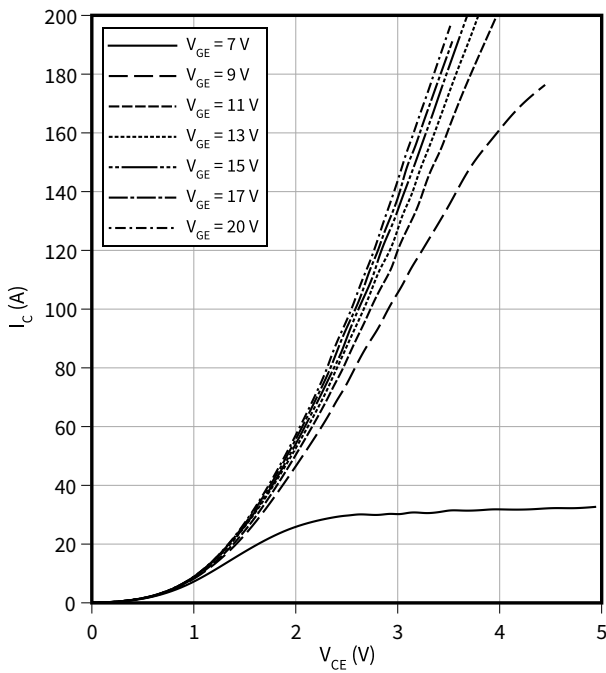
Typical output characteristic

$I_C = f(V_{CE})$
 $T_{vj} = 25\text{ °C}$



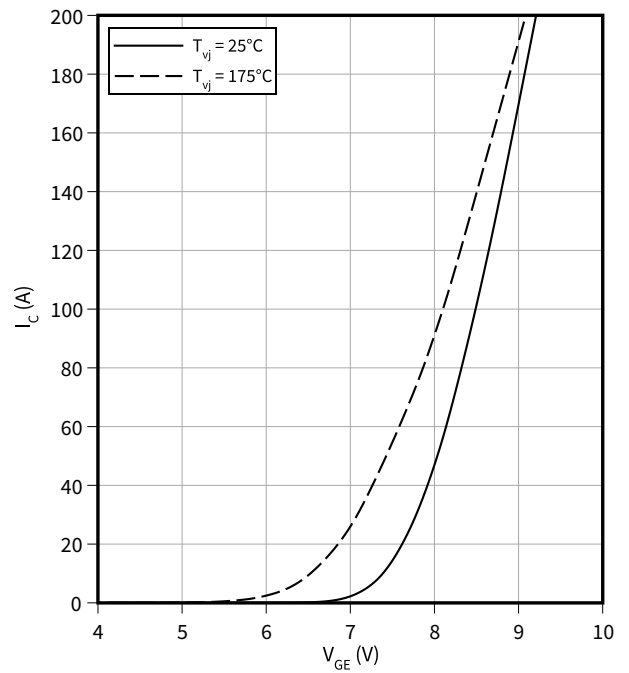
Typical output characteristic

$I_C = f(V_{CE})$
 $T_{vj} = 175\text{ °C}$



Typical transfer characteristic

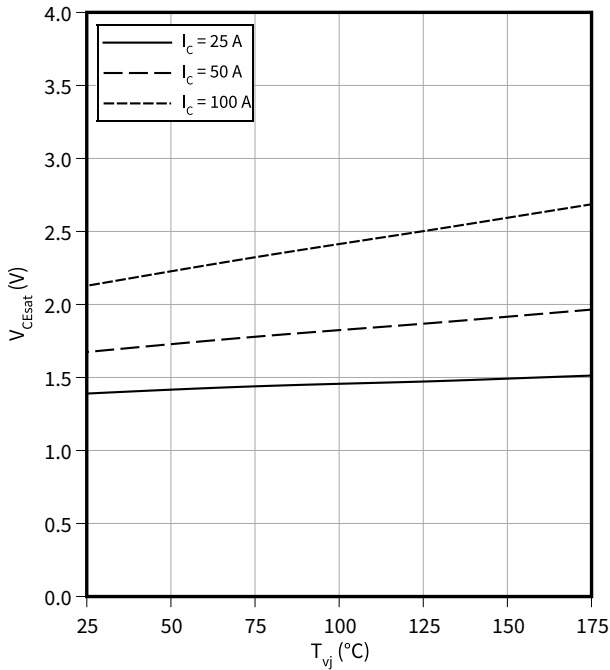
$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



4 Characteristics diagrams

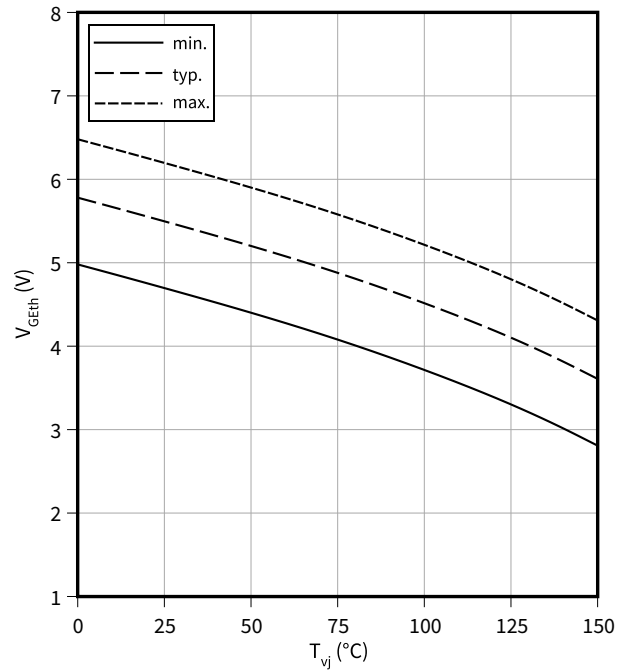
Typical collector-emitter saturation voltage as a function of junction temperature

$V_{CEsat} = f(T_{vj})$
 $V_{GE} = 15 \text{ V}$



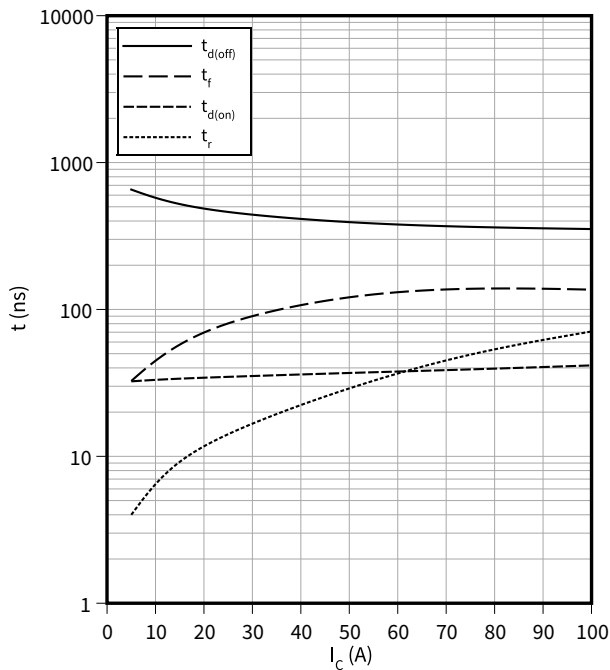
Gate-emitter threshold voltage as a function of junction temperature

$V_{Geth} = f(T_{vj})$
 $I_C = 0.85 \text{ mA}$



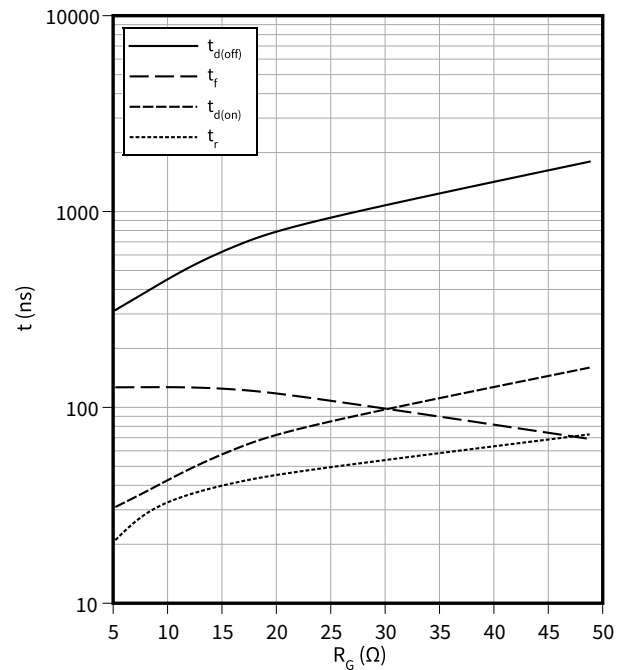
Typical switching times as a function of collector current

$t = f(I_C)$
 $V_{CC} = 600 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = 0/15 \text{ V}, R_G = 8 \text{ } \Omega$



Typical switching times as a function of gate resistor

$t = f(R_G)$
 $I_C = 50 \text{ A}, V_{CC} = 600 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = 0/15 \text{ V}$

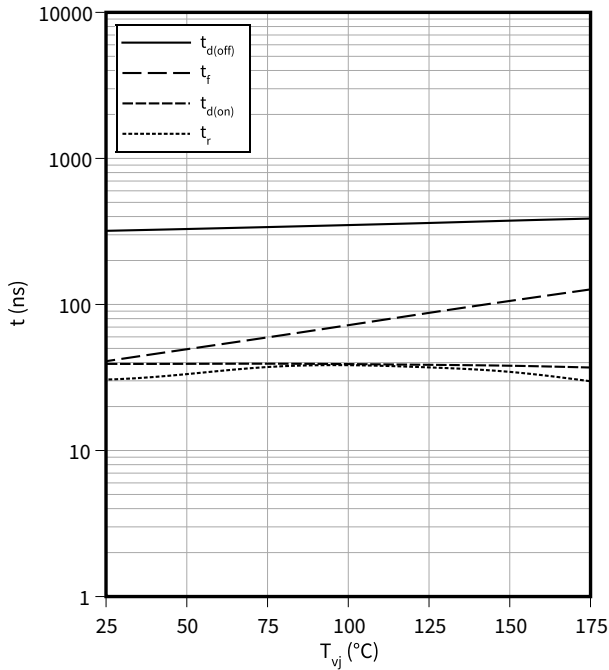


4 Characteristics diagrams

Typical switching times as a function of junction temperature

$t = f(T_{vj})$

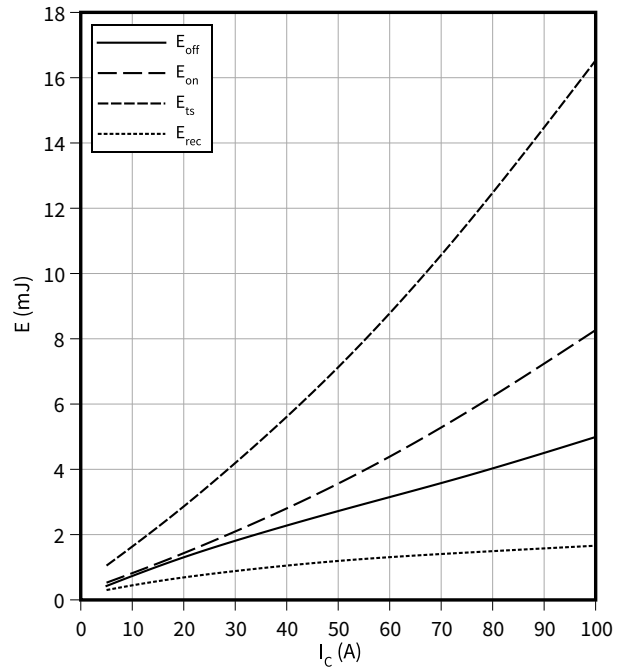
$I_C = 50 \text{ A}, V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_G = 8 \Omega$



Typical switching energy losses as a function of collector current

$E = f(I_C)$

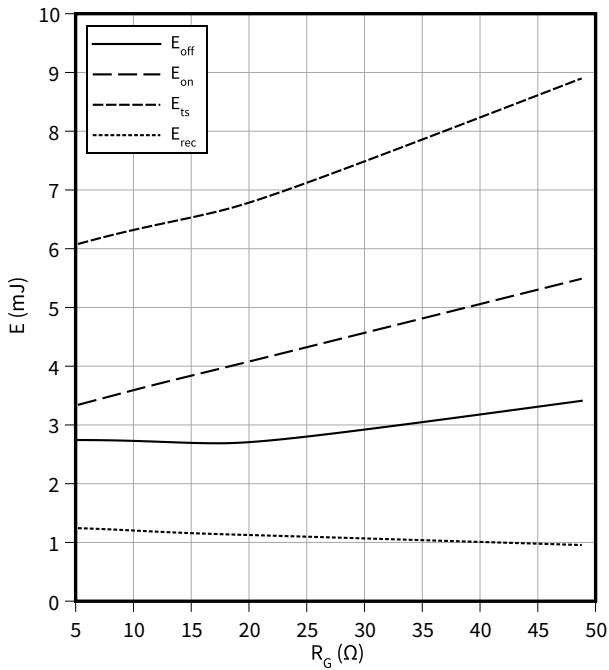
$V_{CC} = 600 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = 0/15 \text{ V}, R_G = 8 \Omega$



Typical switching energy losses as a function of gate resistor

$E = f(R_G)$

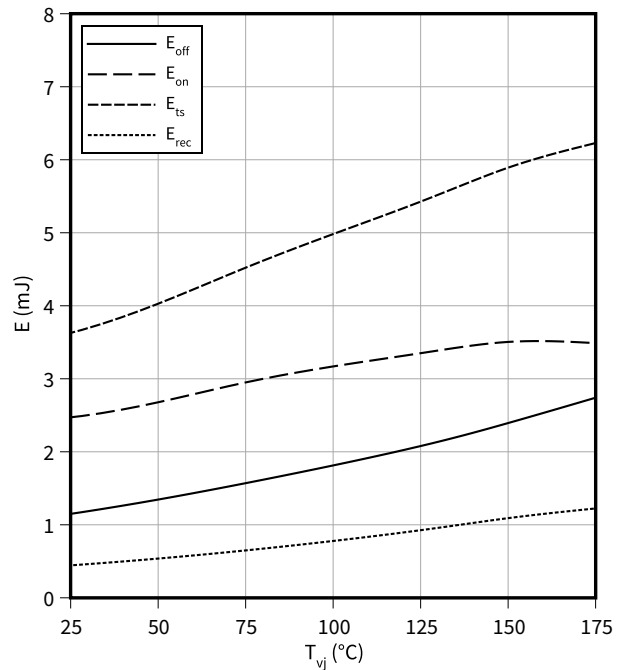
$I_C = 50 \text{ A}, V_{CC} = 600 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = 0/15 \text{ V}$



Typical switching energy losses as a function of junction temperature

$E = f(T_{vj})$

$I_C = 50 \text{ A}, V_{CC} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, R_G = 8 \Omega$

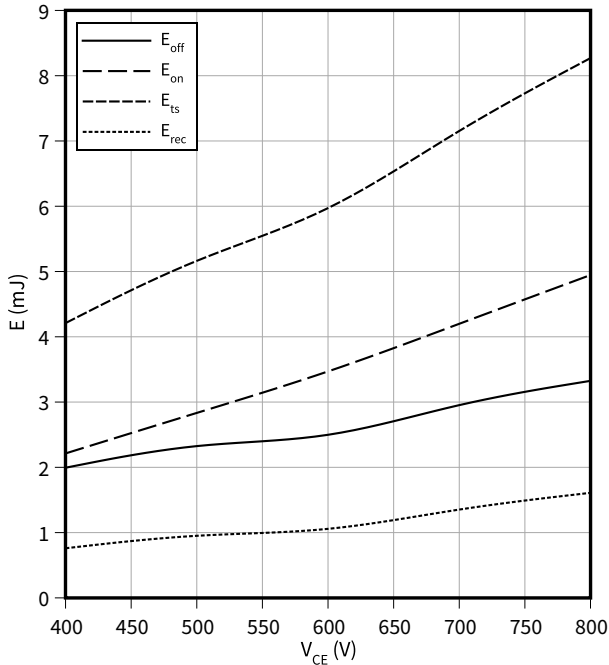


4 Characteristics diagrams

Typical switching energy losses as a function of collector emitter voltage

$E = f(V_{CE})$

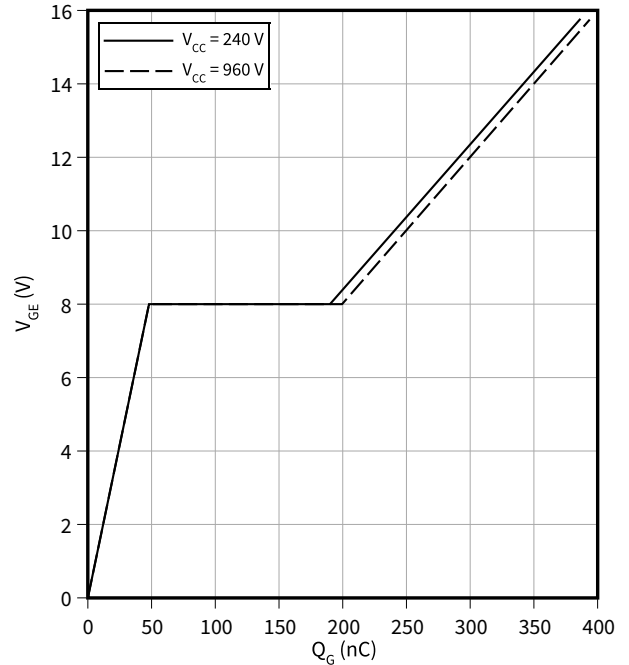
$I_C = 50 \text{ A}$, $T_{vj} = 175 \text{ °C}$, $V_{GE} = 0/15 \text{ V}$, $R_G = 8 \text{ } \Omega$



Typical gate charge

$V_{GE} = f(Q_G)$

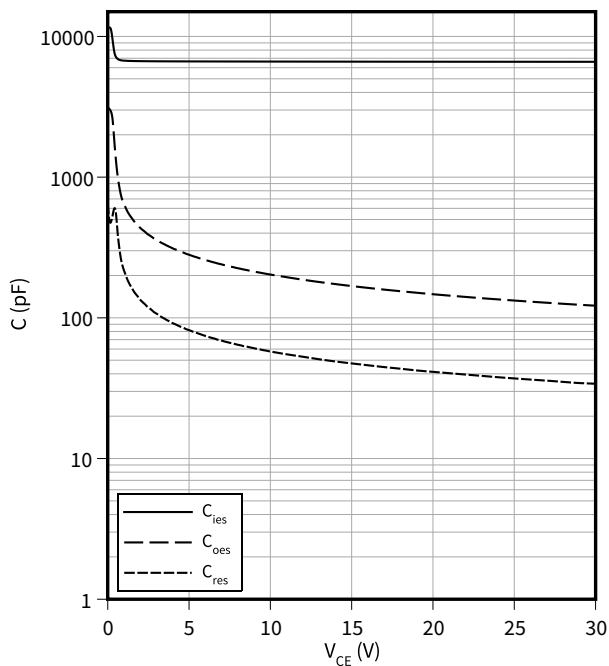
$I_C = 50 \text{ A}$



Typical capacitance as a function of collector-emitter voltage

$C = f(V_{CE})$

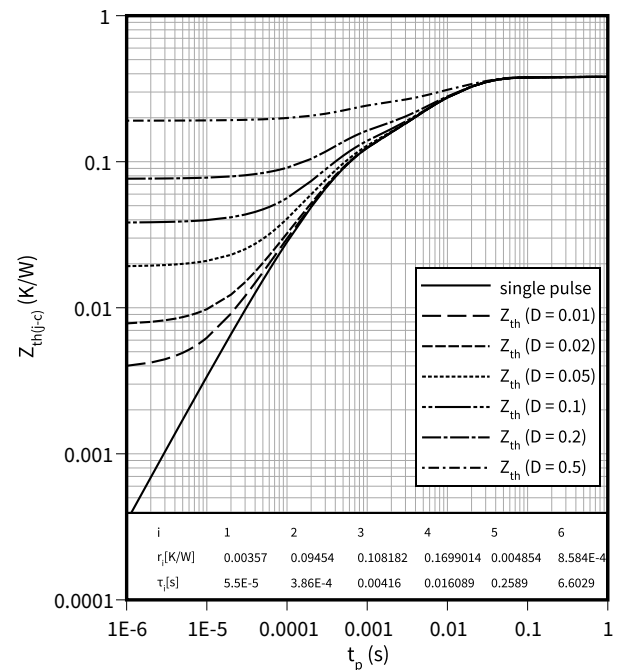
$f = 100 \text{ kHz}$, $V_{GE} = 0 \text{ V}$



IGBT transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$

$D = t_p/T$

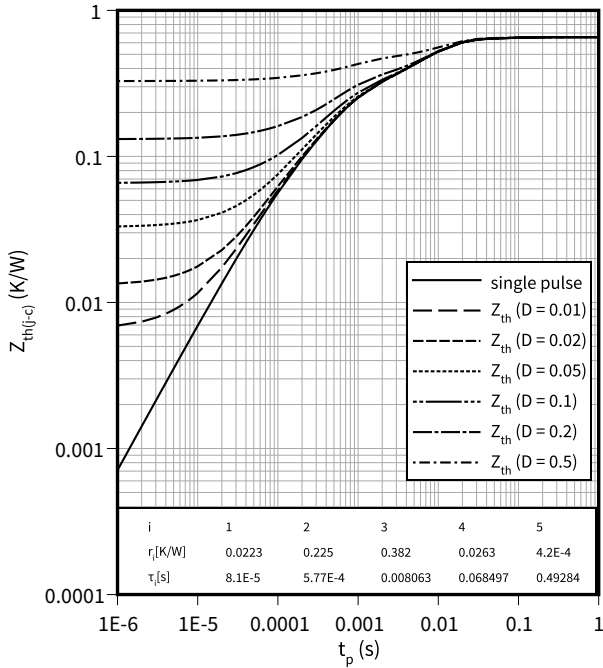


4 Characteristics diagrams

Diode transient thermal impedance as a function of pulse width

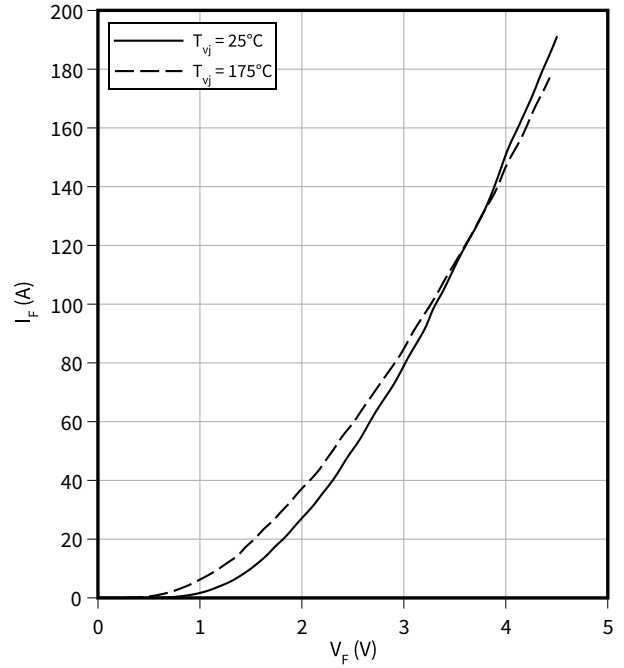
$$Z_{th(j-c)} = f(t_p)$$

$$D = t_p/T$$



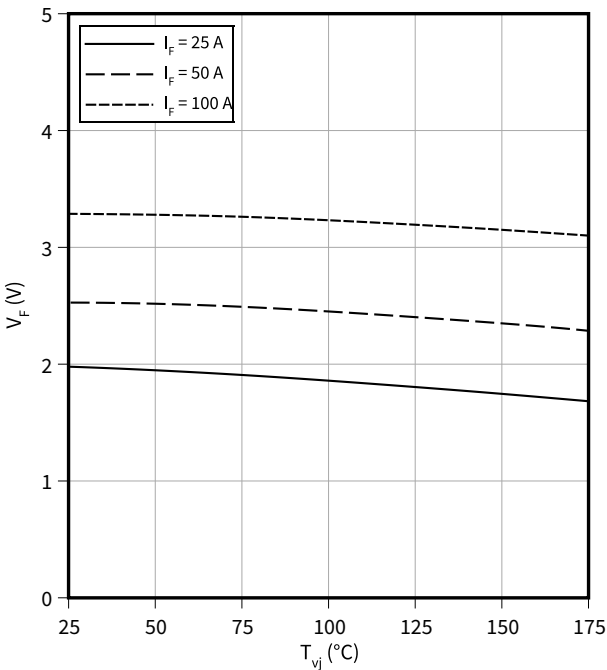
Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



Typical diode forward voltage as a function of junction temperature

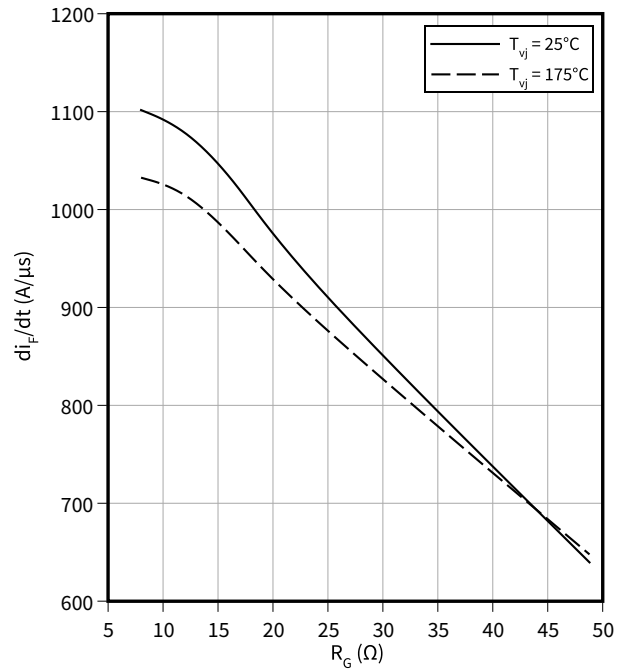
$$V_F = f(T_{vj})$$



Typical diode current slope as a function of gate resistor

$$di_F/dt = f(R_G)$$

$$V_R = 600 \text{ V}, I_F = 50 \text{ A}$$

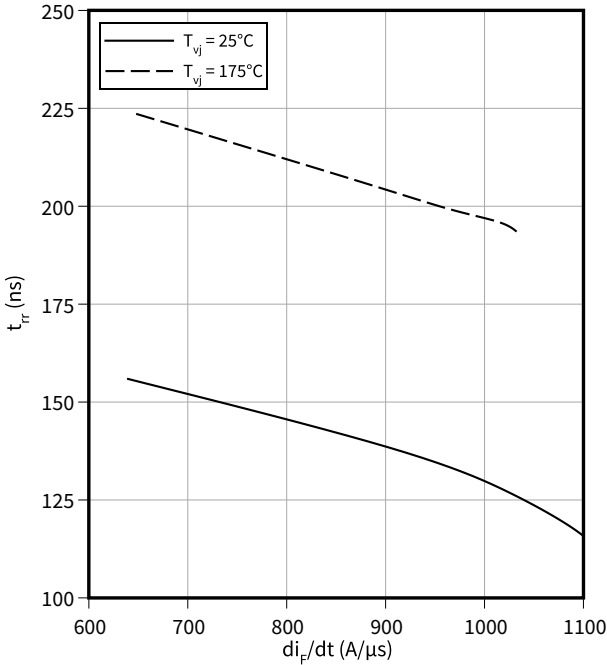


4 Characteristics diagrams

Typical reverse recovery time as a function of diode current slope

$t_{rr} = f(di_F/dt)$

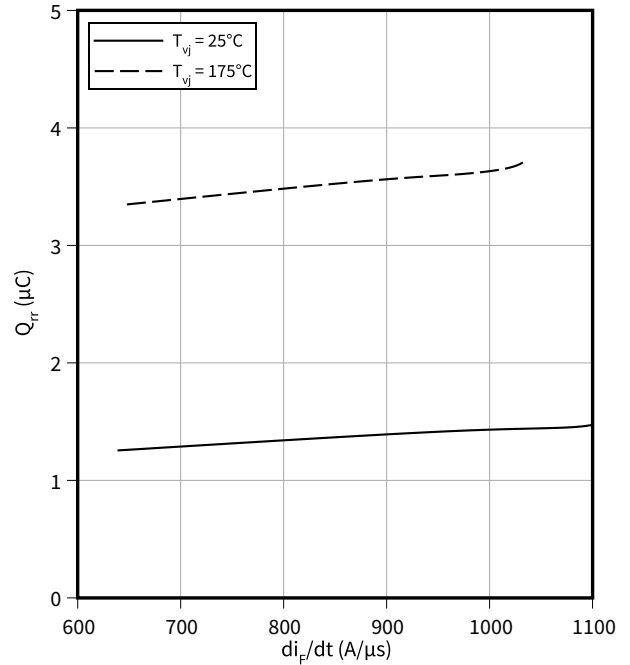
$V_R = 600\text{ V}, I_F = 50\text{ A}$



Typical reverse recovery charge as a function of diode current slope

$Q_{rr} = f(di_F/dt)$

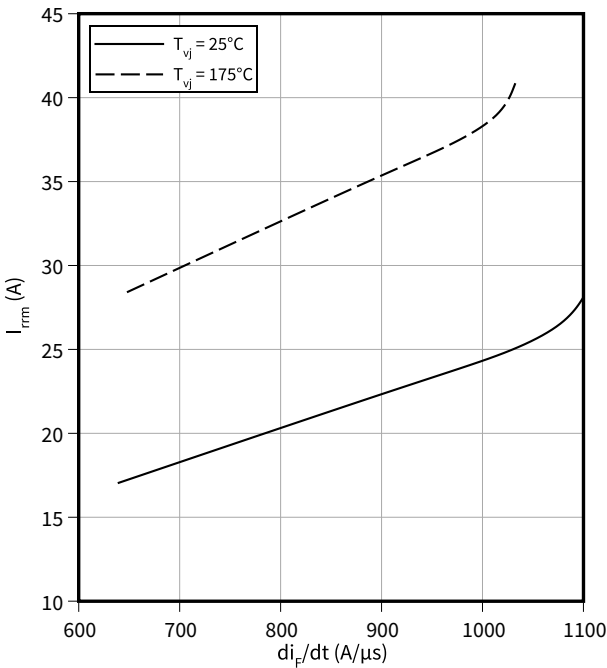
$V_R = 600\text{ V}, I_F = 50\text{ A}$



Typical reverse recovery current as a function of diode current slope

$I_{rrm} = f(di_F/dt)$

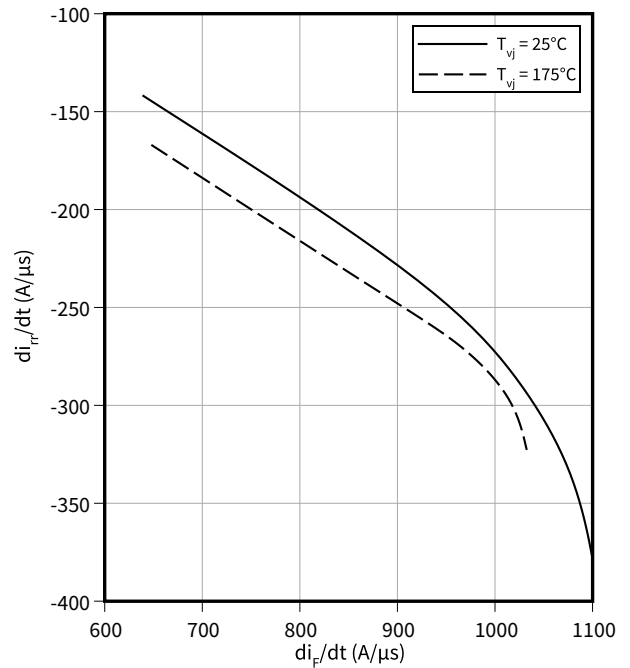
$V_R = 600\text{ V}, I_F = 50\text{ A}$



Typical diode peak rate of fall of reverse recovery current as a function of diode current slope

$di_{rr}/dt = f(di_F/dt)$

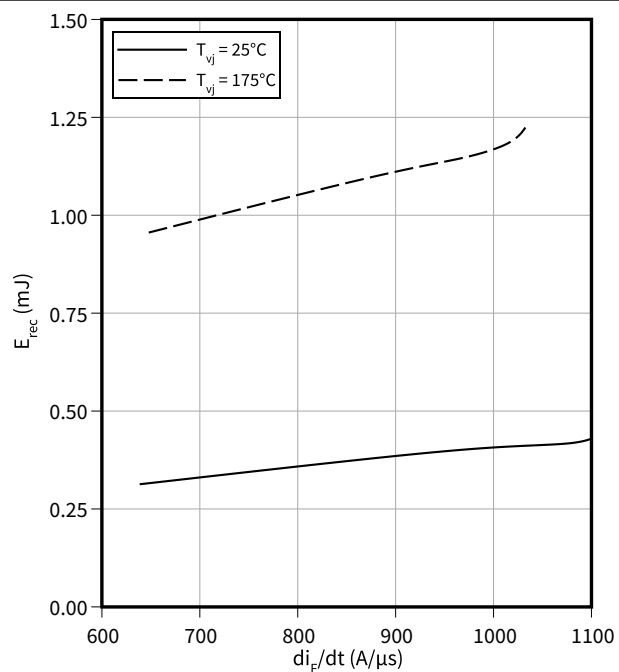
$V_R = 600\text{ V}, I_F = 50\text{ A}$



Typical reverse energy losses as a function of diode current slope

$$E_{rec} = f(di_F/dt)$$

$V_R = 600 \text{ V}$, $I_F = 50 \text{ A}$



5 Package outlines

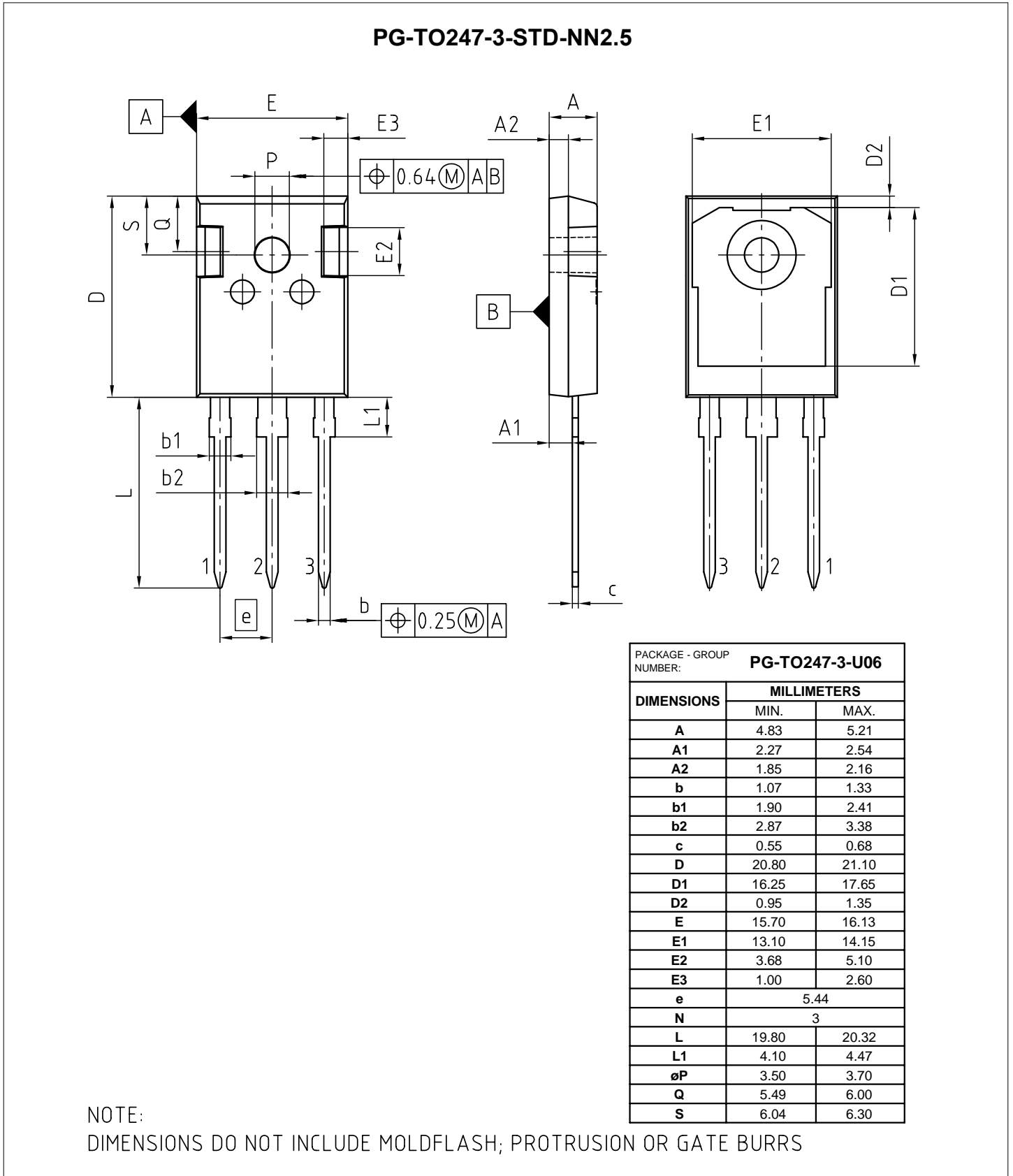


Figure 1

6 Testing conditions



Figure 2

Revision history

Document revision	Date of release	Description of changes
0.10	2022-05-02	Target datasheet
0.20	2022-05-19	Editorial changes
0.30	2022-06-01	Editorial changes
1.00	2022-11-02	Final datasheet
1.10	2022-11-25	Update of potential applications

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